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Qualcomm Collaborates with Microsoft to Accelerate Cloud Services on 10nm Qualcomm Centriq 2400 Platform

--Contributes Server Specification to Open Compute Project--

SANTA CLARA, Calif., March 8, 2017 /PRNewswire/ -- At Open Compute Project (OCP) Summit 2017, Qualcomm Incorporated (NASDAQ: QCOM), through its subsidiary, Qualcomm Datacenter Technologies, Inc. (QDT), today announced a collaboration with Microsoft to accelerate next generation cloud services on its 10 nanometer Qualcomm Centriq™ 2400 platform. This collaboration will span multiple future generations of hardware, software and systems.

With the goal of enabling a variety of cloud workloads to run on the Microsoft Azure cloud platform powered by Qualcomm Centriq 2400 server solutions, QDT today submitted a server specification using its advanced 10 nanometer Qualcomm Centriq 2400 platform to OCP. The Qualcomm Centriq 2400 Open Compute Motherboard server specification is based on the latest version of Microsoft's Project Olympus. Moreover, QDT today conducted the first public demonstration of Windows Server, developed for Microsoft's internal use, powered by the Qualcomm Centriq 2400 processor.

QDT has been working with Microsoft for several years on ARM-based server enablement and has onsite engineering at Microsoft to collaboratively optimize a version of Windows Server, for Microsoft's internal use in its data centers, on Qualcomm Centriq 2400-based systems. QDT's OCP submission is the result of a multi-faceted, multi-level engagement between the two companies to facilitate ARM adoption into the data center. It encompasses multiple areas of hardware and software including board development, firmware, operating system, compilers and tools, and CoreCLR.

The Qualcomm Centriq 2400 Open Compute Motherboard pairs QDT's recently announced 10nm, 48-core server processor with the most advanced interfaces for memory, network, and peripherals enabling the OCP community to access and design ARM-based servers for the most common cloud compute workloads. It fits into a standard 1U server system, offering system vendors the flexibility to create innovative, configurable designs for compute-intensive data center workloads. It can be paired with compute accelerators, multi-host NICs, and leading-edge storage technologies such as NVMe to optimize performance for specific workloads.

"QDT is accelerating innovation in data centers by delivering the world's first 10nm server platform," said Ram Peddibhotla, vice president, product management, Qualcomm Datacenter Technologies, Inc. "Our collaboration with Microsoft and contribution to the OCP community enables innovations such as Qualcomm Centriq 2400 to be designed in and deployed into the data centers rapidly. In collaborating with Microsoft and other industry leading partners, we are democratizing system design and enabling a broad-based ARM server ecosystem."

"Microsoft and QDT are collaborating with an eye to the future addressing server acceleration and memory technologies that have the potential to shape the data center of tomorrow," said Dr. Leendert van Doorn, distinguished engineer, Microsoft Azure, Microsoft Corp. "Our joint work on Windows Server for Microsoft's internal use, and the Qualcomm Centriq 2400 Open Compute Motherboard server specification, compatible with Microsoft's Project Olympus, is an important step toward enabling our cloud services to run on QDT-based server platforms."

As a sign of further support and commitment to this ecosystem, QDT is also pleased to announce that it has joined the Open Compute Project Foundation as a gold member. The Qualcomm Centriq 2400 motherboard contribution to OCP underscores not only open hardware innovation but also enablement by technology partners to deliver enterprise-level OS, firmware, co-processors, interconnects, Java and other technologies to enable ARM ecosystems in the data center. QDT continues to work with leading companies including Red Hat, Canonical, Mellanox, Xilinx, and AMI, to enable a rich ecosystem for market readiness and software build-out.

The Qualcomm Centriq 2400 Open Compute Motherboard will be on display at Microsoft's booth A4 and in Mellanox booth C-23 at the 2017 OCP US Summit in Santa Clara, Calif., on March 8 and 9.

About Qualcomm

Qualcomm's technologies powered the smartphone revolution and connected billions of people. We pioneered 3G and 4G – and now we are leading the way to 5G and a new era of intelligent, connected devices. Our products are revolutionizing industries, including automotive, computing, IoT, healthcare and data center, and are allowing millions of devices to connect

with each other in ways never before imagined. Qualcomm Incorporated includes our licensing business, QTL, and the vast majority of our patent portfolio. Qualcomm Technologies, Inc., a subsidiary of Qualcomm Incorporated, operates, along with its subsidiaries, all of our engineering, research and development functions, and all of our products and services businesses, including, our QCT semiconductor business. To learn more, visit Qualcomm's [website](#), [blog](#), [Twitter](#) and [Facebook](#) pages.

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